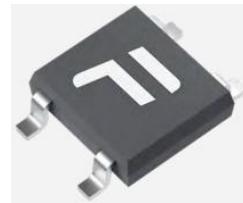
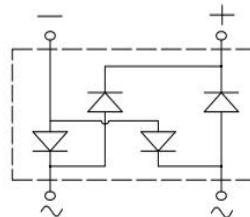


Bridge Rectifier Diode 整流桥

■Features 特点

Glass passivated chip junction 玻璃钝化结
 High surge current capability 高浪涌电流能力
 Reflow Solder Temperature 220°C 回流焊温度 220 度
 Package 封装: MBS



■Maximum Rating 最大额定值

($T_A=25^\circ\text{C}$ unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	MB05SA	MB1SA	MB2SA	MB4SA	MB6SA	MB8SA	MB10SA	Unit 单位
Marking 印字		MB05S	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	
Peak Reverse Voltage 反向峰值电压	V_{RRM}	50	100	200	400	600	800	1000	V
DC Reverse Voltage 直流反向电压	$V_{R(DC)}$	50	100	200	400	600	800	1000	V
RMS Reverse Voltage 反向电压均方根值	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Forward Rectified Current 正向整流电流	I_F				1				A
Peak Surge Current 峰值浪涌电流	I_{FSM}				30				A
Thermal Resistance J-A 结到环境热阻	$R_{\theta JA}$				75				°C/W
Junction Temperature 结温	T_J				150				°C
Storage Temperature 储藏温度	T_{stg}				-55 to +150 °C				

■Electrical Characteristics 电特性

($T_A=25^\circ\text{C}$ unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位	Condition 条件
Forward Voltage 正向电压降	V_F		1.0		V	$I_F=0.5\text{A}$
Reverse Current ($T_A=25^\circ\text{C}$) 反向漏电流($T_A=125^\circ\text{C}$)	I_R			5 500	uA	$V_R=V_{RRM}$
Diode Capacitance 二极管电容	C_D		13		pF	$V_R=4\text{V}, f=1\text{MHz}$

■Typical Characteristic Curve 典型特性曲线

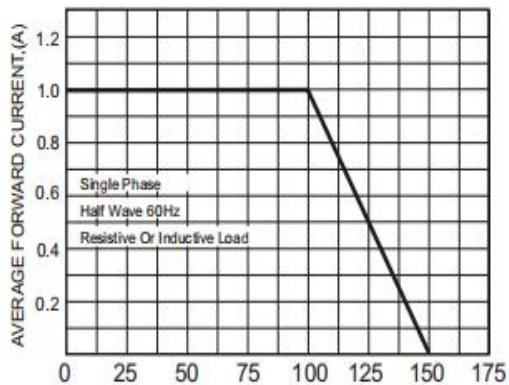


Figure 1: Forward Current Derating Curve

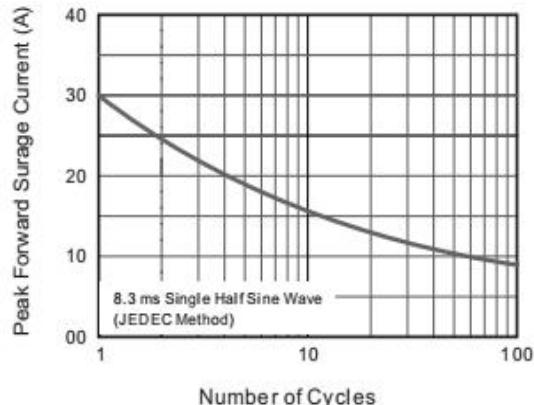


Figure 2: Peak Forward Surge Current

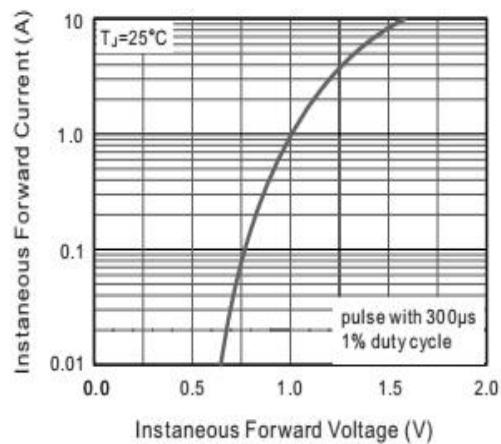


Figure 3: Instantaneous Forward Characteristics

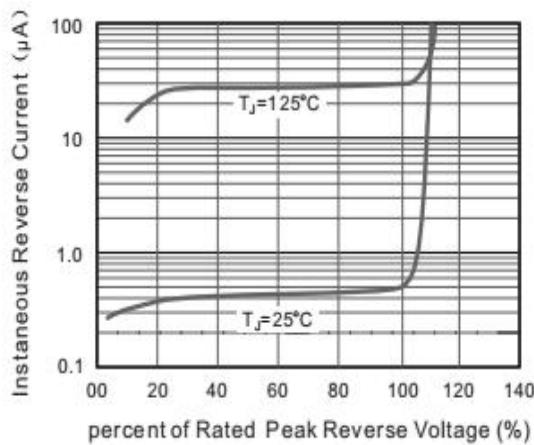
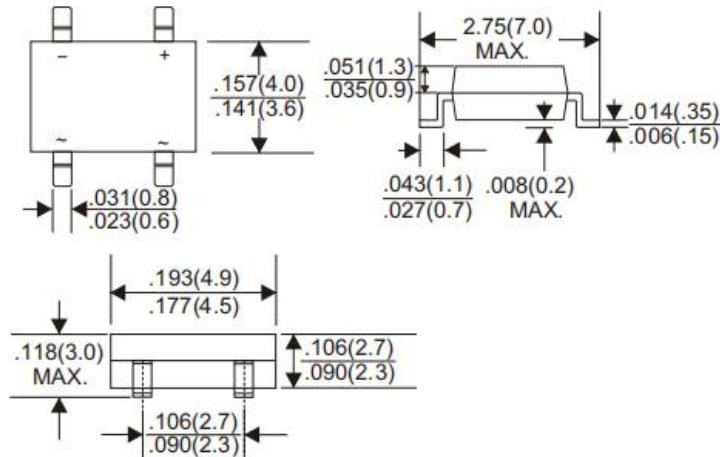


Figure 4: Reverse Leakage Characteristics

■Dimension 外形封装尺寸



Dimensions in inches and (millimeters)